Specifications

Drawing No.	USY1M-H1-16424-00	1 / 11
Issued Date.	Apr,19,2016	

Messrs: KED USA

Note: Part Number will be revised in case of specification change.

Product Type	Quartz Crystal
Series	CX2016DB24000D0FLJC6
Frequency	Refer to Doc No.USY1M-H1-16424-00 Page 3/11
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	Refer to Doc No.USY1M-H1-16424-00 Page 3/11
Remarks Pb-Free, RoHS Compliant, MSL	.1

Customer Approval

Approval Signature	Approved Date	
	Department	
	Person in charge	

Seller KYOCERA Crystal Device Corporation

(Sales Division) 6 Takeda Tobadono-cho, Fushimi-ku, Kyoto 612-8501 Japan

TEL. No. 075-604-3500 FAX. No. 075-604-3501

Manufacturer KYOCERA Crystal Device Corporation

Crystal Units Division 5850, Higashine-Koh, Higashine-Shi, Yamagata

999-3701 Japan TEL. No. 0237-43-5611 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Unit Application Engineering Section Crystal Units Division	S.ltoh	T.Soda	A.Muraoka	Y.Nozaki

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Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
00	First Edition	Apr,19,2016	T.Soda	A.Muraoka	Y.Nozaki

[Parts Number list]

Nominal Frequency	KYOCERA Part Number	ESR	Naminal Fraguency Code	
(MHz)	KYOCERA Part Number	(Ω)	Nominal Frequency Code	
19.200	CX2016DB19200D0FLJC1	200	19200	
24.000	CX2016DB24000D0FLJC6	150	24000	
24.576	CX2016DB24576D0FLJC1	150	24576	
25.000	CX2016DB25000D0FLJC2	150	25000	
26.000	CX2016DB26000D0FLJC4	60	26000	
27.000	CX2016DB27000D0FLJC1	60	27000	
30.000	CX2016DB30000D0FLJC1	60	30000	
38.400	CX2016DB38400D0FLJC2	60	38400	
48.000	CX2016DB48000D0FLJC1	50	48000	

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1. APPLICATION

The purpose of this document is applied to CX2016DB quartz crystal.

2. KYOCERA PART NUMBER

Refer to Doc No.USY1M-H1-16424-00 Page 3/11

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature range	Topr	-30~+85	deg. C	
Storage Temperature range	Tstg	-40~+85	deg. C	

4. CHARACTERISTICS

4-1 ELECTRICAL CHARACTERISTICS

lt		Electrical Specification				To at Oom dition	Danasila
Items	SYMB.	Min	Тур.	Max	Unit	Test Condition	Remarks
Mode of Vibration		F	undame	ntal			
Nominal Frequency	F0		24		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		8.0		pF		
Frequency Tolerance	df/F	-10.0		+10.0		+25±3°C	
Frequency Temperature characteristics	df/F	-15.0		+15.0	PPM	-30°C ~+85°C	
Frequency Ageing Rate		-1.0		+1.0		1 ST year	+25±3°C
Equivalent Series Resistance	ESR		(*2)		Ω		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			ΜΩ	100V(DC)	

Measurement Condition

Frequency measurement

Measuring instrument : IEC PI-Network Test Fixture

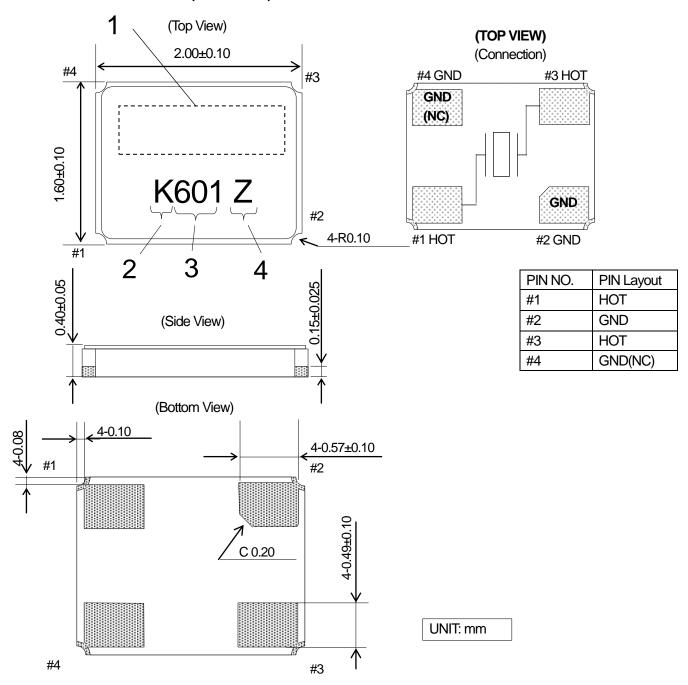
IEC 60444-8 STD (Pi circuit 41901A) Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series

^{*1 *2} Refer to Doc No.USY1M-H1-16424-00 Page 3/11

5. APPEARANCES, PHYSICAL DIMENSION OUTLINE DIMENSION (not to scale)



MARKING

1 Nominal Frequency First 5digit of the frequency is indicated. *3

2 Identification [K] is to indicate 1Pin direction.

3 Date Code Last 1 Digit of YEAR and WEEK (Ex) 2016, Jan, 01 → 601

4 Manufacturing Location Y→Japan (Yamagata)

Z→Japan (Shiga Yohkaichi)

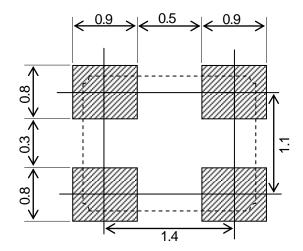
T→Thailand

*The font of marking is for reference only.

*3 Refer to Doc No.USY1M-H1-16424-00 Page 3/11

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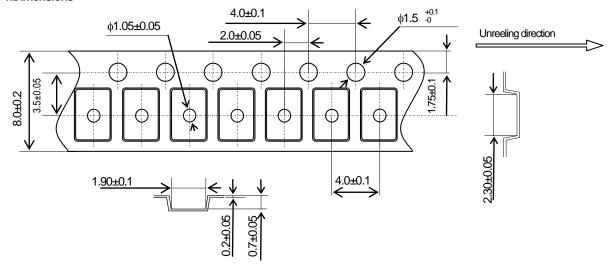
6. RECOMMENDED LAND PATTERN (not to scale)



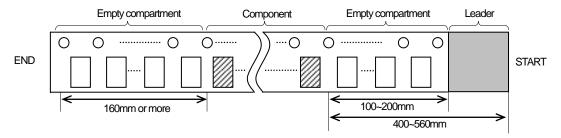
UNIT: mm

7. TAPING & REEL

7-1.Dimensions



7-2.Leader and Carrier tape

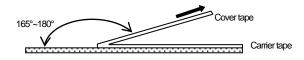


7-3.Direction (Orientation shall be checked from the top cover tape side)

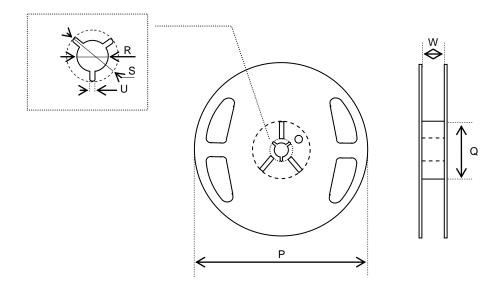


7-4.Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 7-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.



7-5.Reel Specification



ф330 Reel (15,000 pcs Max.)

Symbol	Р	Q	R
Dimension	ф330±2.0	φ100±1.0	φ13±0.2
Symbol	S	U	W
Dimension	ф21±0.8	2.0±0.5	9.4±1.0

(Unit: mm)

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8. Enviromental requirements

After conducting the following tests, component needs to meet below conditions.

Frequency: Fluctuation within +/-10 x 10⁻⁶

CI: Fluctuation within \pm -20% or 5 Ω whichever is larger

8.1 Resistance to Shock Drop Test - test conditions

Part is mounted to 200g fixture and dropped from a height of 150cm to a cement

floor. The drop must be conducted on all 6 mutually perpendicular axes.

Mechanical Shock Rating

Peak Value 100g 6ms Half-Sine

8.2 Resistance to Vibration Test condition

frequency : 10 - 55 - 10 Hz

Amplitude : 1.5mm

Cycle time : 15 minutes

Direction : X,Y,Z (3direction),2h each.

8.3 Resistance to Heat Test condition

The quartz crystal unit shall be stored at a

temperature of +85±2°C for 500h and subjected to room temperature for 1h before measurement.

8.4 Resistance to Cold Test condition

The quartz crystal unit shall be stored at a

temperature of -40±2°C for 500h and subjected to room temperature for 1h before measurement.

8.5 Thermal Shock Test condition

The quartz crystal unit shall be subjected to 500 temperature

cycles shown in table below, Then it shall be subjected

to room temperature for 1h before mesurement.

Cycle :- $40\pm2^{\circ}$ C (30min.) \rightarrow +25 $\pm2^{\circ}$ C(5min.)

→ +85±2°C(30min.)→ +25±2°C(5min.)

8.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of +60±2°C with relative humidity of 90% to 95% for 240 h. Then it shall be subjected to room temperature for 1h before measurement.

8.7 Soldering condition

1.) Type of solder

Material → lead free solder paste Melting point → +220±5°C

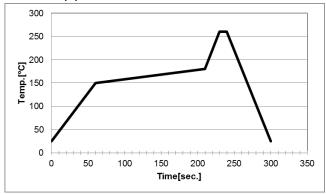
2.) Reflow temp.profile

z., r tonov tomp.promo				
	Temp [°C]	Time[sec]		
Preheating	+150 to +180	150 (typ.)		
Peak	+260±5	10 (max.)		
Total	-	300 (max.)		

Frequency shift : ±2ppm

- 3.) Hand Soldering +350°C 3 sec max
- 4.) Reflow Times 2 times in below Reflow temp. profile

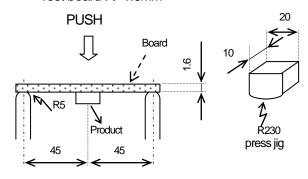
Reflow temp.profile



8.8 Bending Strength

Solder this product in center of the circuit board (40mm X 100mm), and add deflection of 3mm.

Test board: t=1.6mm



UNIT: mm

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9. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

(2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 3 times the ESR (Equivalent Series Resistance) of crystal unit.

10. Storage conditions

Please store product in below conditions, and use within 6 months.

Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

11. Manufacturing location

Kyocera Crystal Device Corporation Yamagata Plant

Kyocera Crystal Device Corporation Shiga Yohkaichi Plant

Kyocera Crystal Device (Thailand) Co., Ltd

12. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

13. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waivered.

14. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.